

YETDA INDUSTRY LTD.

Technical Data Sheet

MODEL NO : S192ANB4

0603Package 1.6*0.8mm Chip LEDs

Features :

- Package in 8mm tape on 7" diameter reel
- Compatible with automatic placement equipment
- Compatible with reflow solder process

Applications :

- Indicators
- Automotive : backlighting in dashboard and switch
- Backlight for LCD

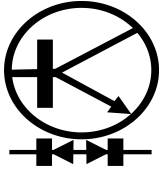
Dice material	Emitted color	Lens Color
InGaN	Blue	Water Clear

Electrical /Optical Characteristics(Ta=25°C)

Parameter	Test Condition	Symbol		Value			Unit
				Min	Typ	Max	
Dominant wavelength	I _F =20mA	λ _D	B		470		nm
Forward voltage	I _F =20mA	V _F	B	2.8		3.5	V
Luminous intensity	I _F =20mA	I _v	B	80		225	mcd
Viewing angle at 50% I _v	I _F =10mA	2θ _{1/2}	B		120		Deg
Reverse current	V _R =5V	I _R	B			10	μA

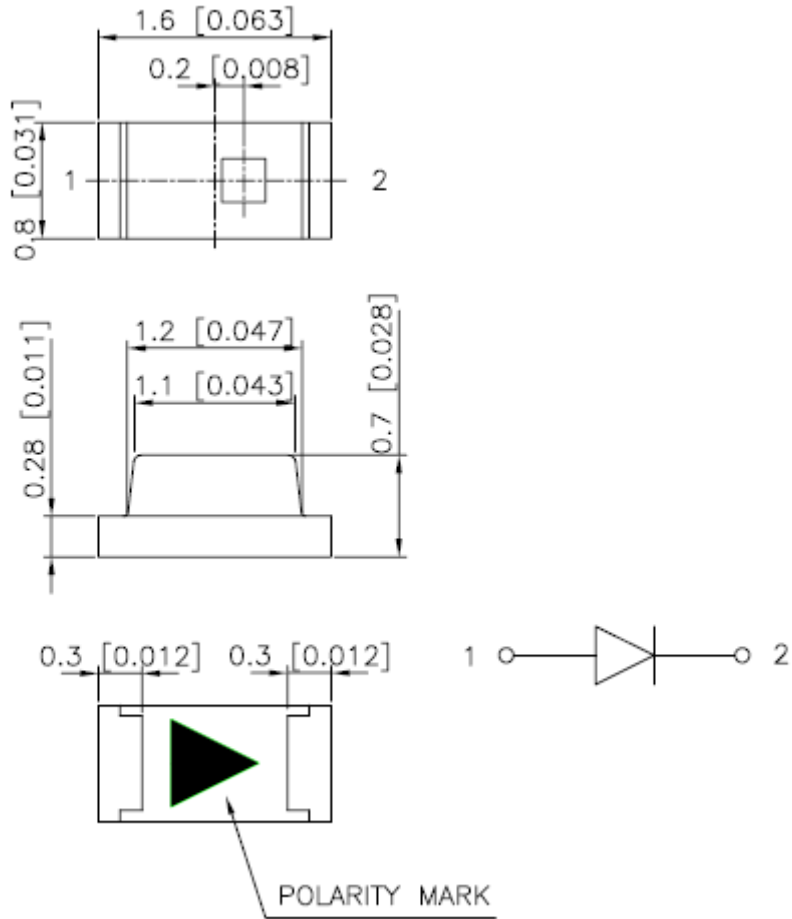
Absolute Maximum Ratings(Ta=25°C)

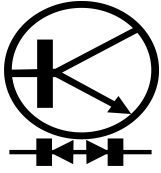
Parameter	Symbol	Value	Unit
Power dissipation	P _d	75	mW
Forward current	I _F	30	mA
Reverse voltage	V _R	5	V
Operating temperature range	Top	-40 ~+80	°C
Storage temperature range	T _{stg}	-40 ~+85	°C
Peak pulsing current (1/8 duty f=1kHz)	I _{FP}	125	mA



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PACKAGING DIMENSIONS (mm):

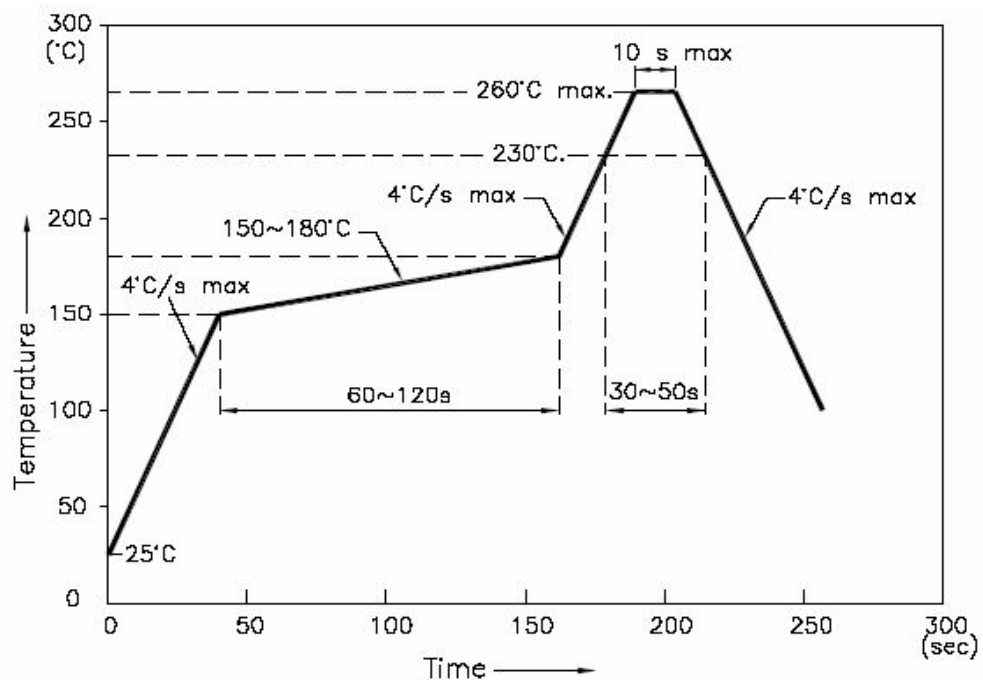




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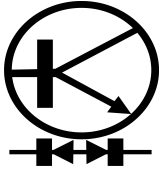
Precautions For Use :
Over– current– proof
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)
Storage
1. The operation of temperature and R.H. are : $5^{\circ}\text{C} \sim 30^{\circ}\text{C}$, 60%R.H. Max.
2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date) .
3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 15hrs.

■ Reflow Temp/Time



NOTES:

1. We recommend the reflow temperature $245^{\circ}\text{C} (\pm 5^{\circ}\text{C})$. the maximum soldering temperature should be limited to 260°C .
2. dont cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.



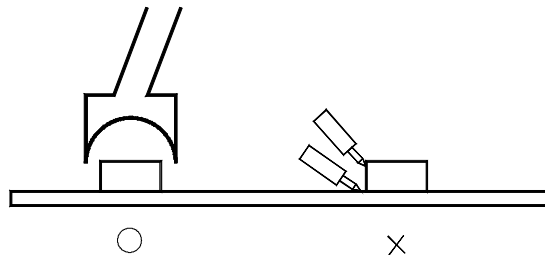
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■Soldering iron

Basic spec is $\leq 5\text{sec}$ when 260°C . If temperature is higher, time should be shorter ($+10^\circ\text{C} \rightarrow -1\text{sec}$). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C .

■Rework

1. Customer must finish rework within 5 sec under 260°C .
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



- Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.